

## **List of Industry Verticals under which application can be submitted for online allotment of land at Sonarpur Hardware Park**

The proposed industry to be established by the entrepreneurs at the Sonarpur Hardware Park should fall under the category of electronic hardware manufacturing industry. In this regard, an indicative list of different electronic hardware industry verticals is given hereunder. During online submission of application form for allotment of land at Sonarpur Hardware Park, entrepreneurs need to select one of the above mentioned verticals (listed below) against the "Type of Industry" field along with an added option as "other electronic hardware product manufacturing" for such verticals which are not listed in the below list. If entrepreneur selects the "other electronic hardware product manufacturing" option then the details of the industry proposed by the entrepreneur will have to be given by manual entry along with proper justification that the proposed industry vertical is falling under the electronic hardware manufacturing industry.

### **Indicative List of verticals under which application can be submitted:-**

#### Electronic Products:-

- Telecom Products
- Nano Electronic Products
- IT Hardware
- Consumer Electronics
- Health and Medical Electronics
- Strategic & Security Electronics
- Solar Photovoltaic including thin film, polysilicon etc.
- Light Emitting Diodes (LED)
- Liquid Crystal Displays (LCDs)
- Avionics
- Industrial Electronics Products
- E-waste processing recycling
- Automotive Electronics
- Agri-Electronics
- Energy Conservation Electronics
- Opto- Electronics
- Bio-metric and identity devices RFID
- Power Supplies for ESDM products
- Home Fuel Cells
- Machine to Machine (M2M) and Internet of Things (IOT) products
- Microprocessor and micro controller manufacturing
- Other electronic hardware product manufacturing

#### Intermediaries:-

- Nano Electronics Components
- Semi-conductor wafering
- Semiconductor Chips including logic, memory and analog
- All Assembly, Testing, Marking and Packaging of ESDM Units
- Chip Components
- Discrete Semiconductors like Transistors, Diodes
- Power Semiconductors (including diffusion) like FETs, MOSFETS, SCRs, GTDs, IGBT etc.
- Electromechanical Components and Mechanical parts as Multilayer PCBs, Transformers, Coils, Connectors, Switches, Ferrites, Micro Motors, Stepper Motors, Films etc.
- Consumables and Accessories such as Mobile Phones and IT accessories-Batteries, Chargers etc. PCB, Foil, Tapes, Epoxy, Cabinet etc.
- All Fabrication Manufacturing facilities (Fabs) for ESDM products